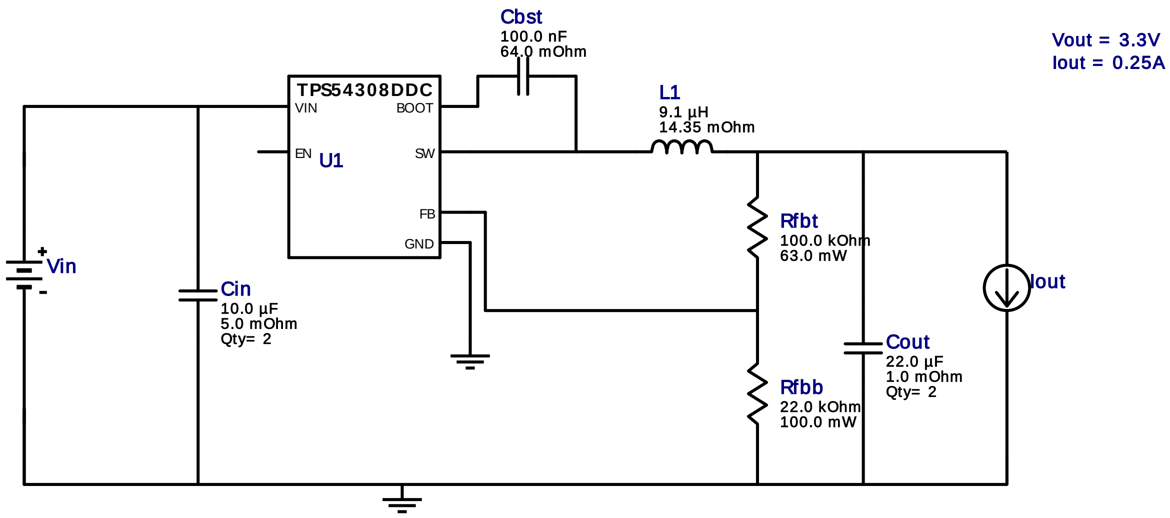
WEBENCH® Design Report

VinMin = 12.8V
VinMax = 16.8V
Vout = 3.3V
Iout = 0.25A

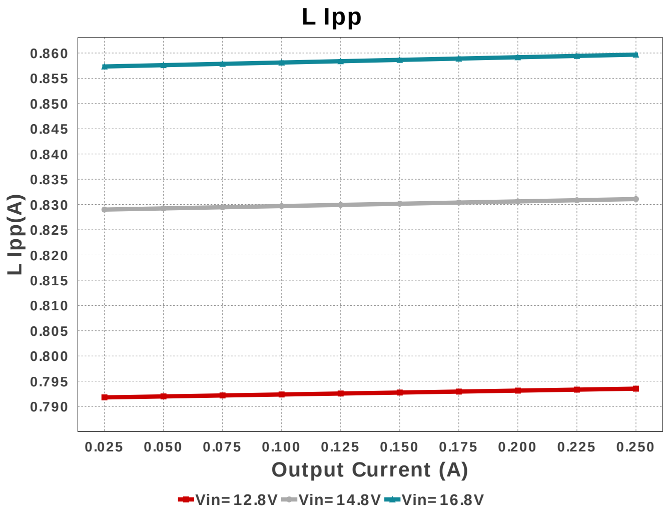
Device = TPS54308DDCR
Topology = Buck
Created = 2020-03-28 21:42:42.974
BOM Cost = $3.76
BOM Count = 9
Total Pd = 0.07W

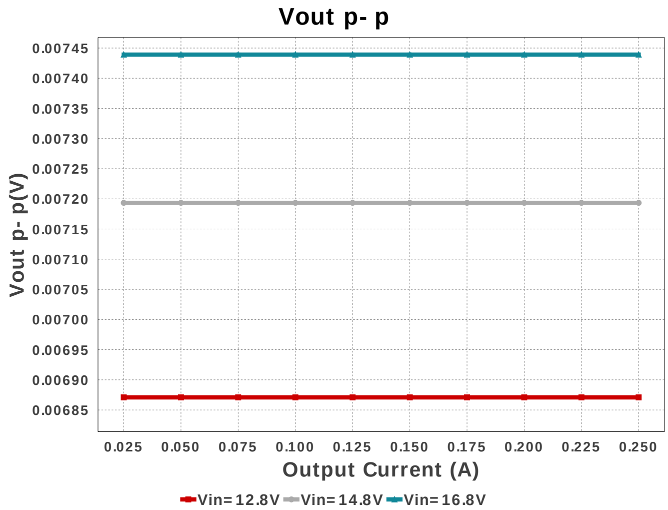
Design : 132 TPS54308DDCR
TPS54308DDCR 12.8V-16.8V to 3.30V @ 0.25A

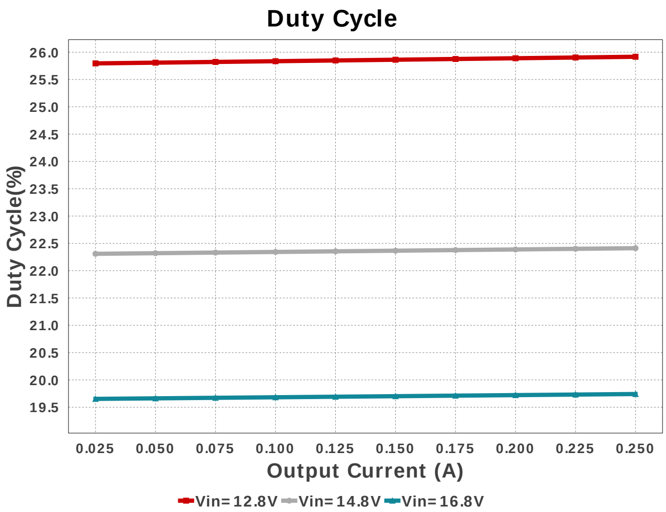


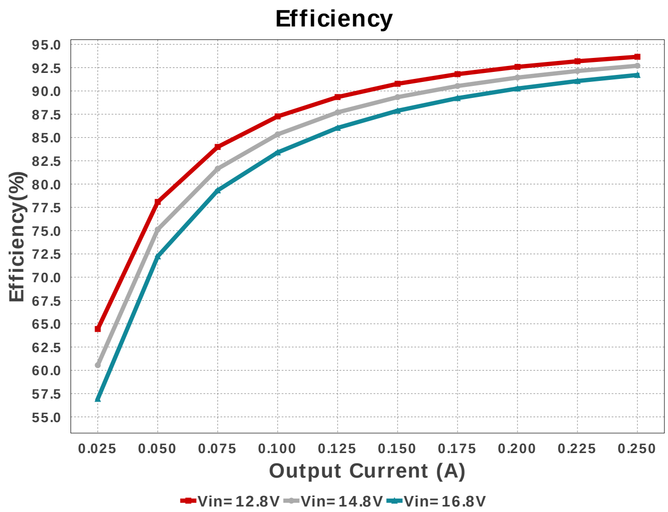
Electrical BOM

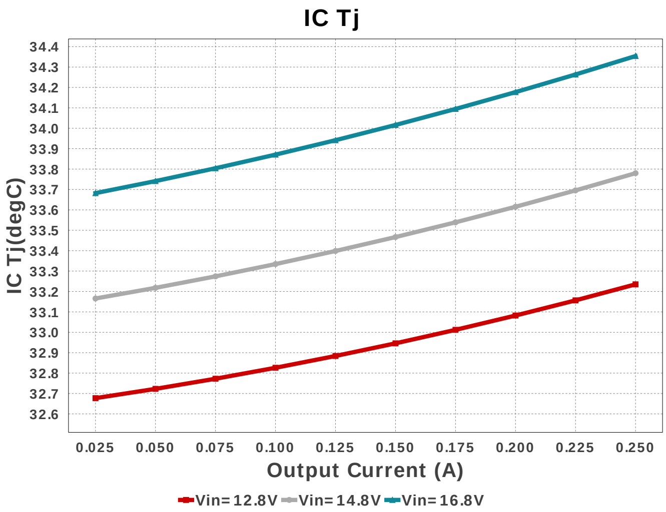
Name	Manufacturer	Part Number	Properties	Qty	Price	Footprint
Cbst	Kemet	C0805C104M5RACTU Series= X7R	Cap= 100.0 nF ESR= 64.0 mOhm VDC= 50.0 V IRMS= 1.64 A	1	$0.01	0805 7 mm^2
Cin	Samsung Electro-Mechanics	CL32B106KBJNNWE Series= X7R	Cap= 10.0 uF ESR= 5.0 mOhm VDC= 50.0 V IRMS= 0.0 A	2	$0.17	1210_270 15 mm^2
Cout	Taiyo Yuden	TMK325B7226KMHP Series= X7R	Cap= 22.0 uF ESR= 1.0 mOhm VDC= 25.0 V IRMS= 0.0 A	2	$0.34	1210_270 15 mm^2
L1	Wurth Elektronik	7447798910	L= 9.1 µH 14.35 mOhm	1	$2.23	WE-PDF_1064 149 mm^2
Rfbb	Yageo	RC0603FR-0722KL Series= ?	Res= 22.0 kOhm Power= 100.0 mW Tolerance= 1.0%	1	$0.01	0603 5 mm^2
Rfbt	Vishay-Dale	CRCW0402100KFKED Series= CRCW..e3	Res= 100.0 kOhm Power= 63.0 mW Tolerance= 1.0%	1	$0.01	0402 3 mm^2
U1	Texas Instruments	TPS54308DDCR	Switcher	1	$0.48	DDC0006A_N 10 mm^2

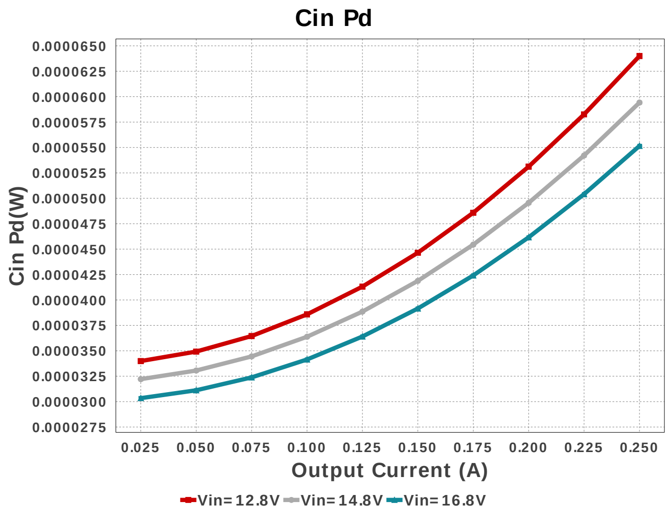

L Ipp
L Ipp(A)
Output Current (A)
Vin=12.8V Vin=14.8V Vin=16.8V


Vout p- p
Vout p- p(V)
Output Current (A)
Vin=12.8V Vin=14.8V Vin=16.8V

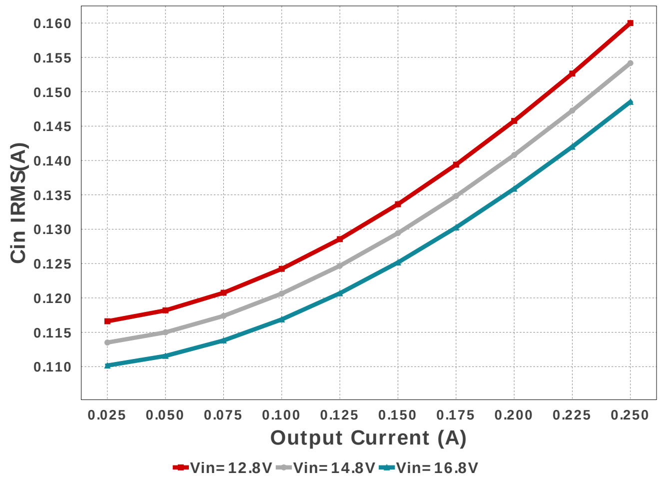

Duty Cycle
Duty Cycle(%)
Output Current (A)
Vin=12.8V Vin=14.8V Vin=16.8V


Efficiency
Efficiency(%)
Output Current (A)
Vin=12.8V Vin=14.8V Vin=16.8V

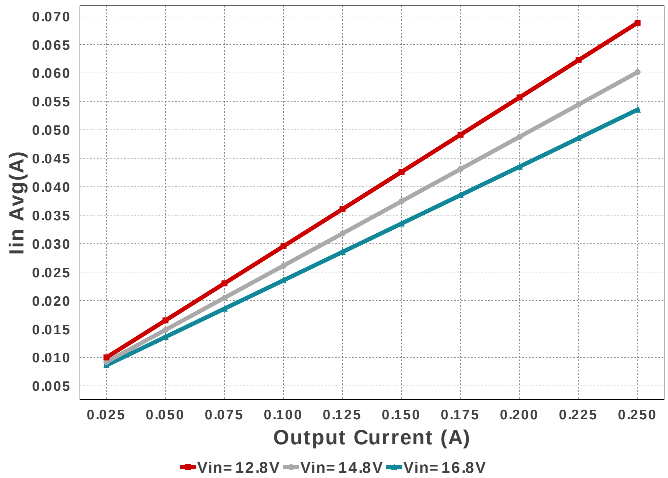

IC Tj
IC Tj(degC)
Output Current (A)
Vin=12.8V Vin=14.8V Vin=16.8V


Cin Pd
Cin Pd(W)
Output Current (A)
Vin=12.8V Vin=14.8V Vin=16.8V

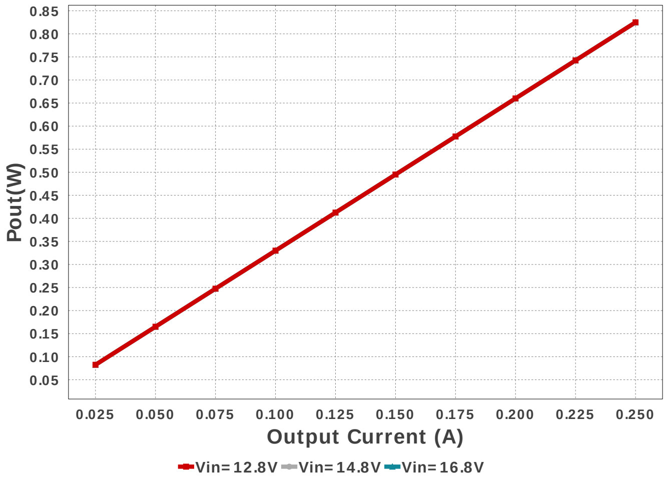
Cin IRMS



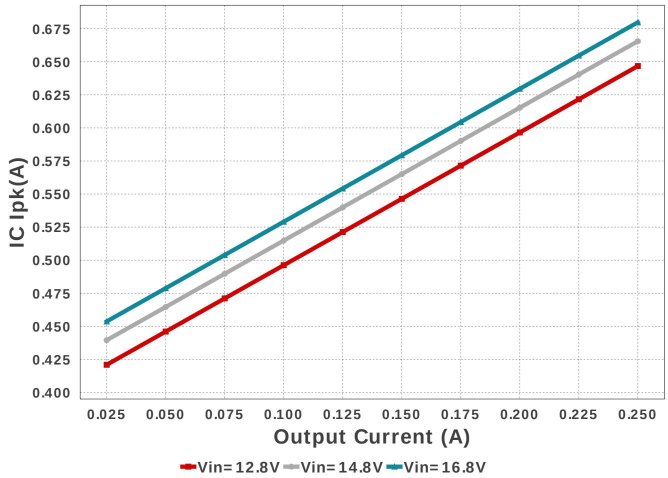
Iin Avg



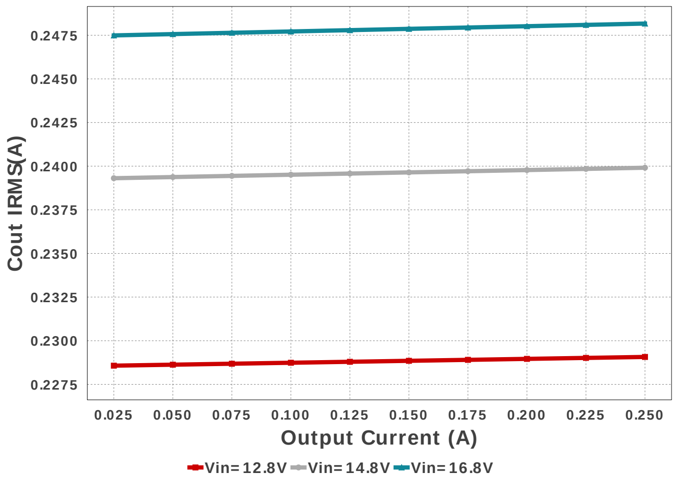
Pout



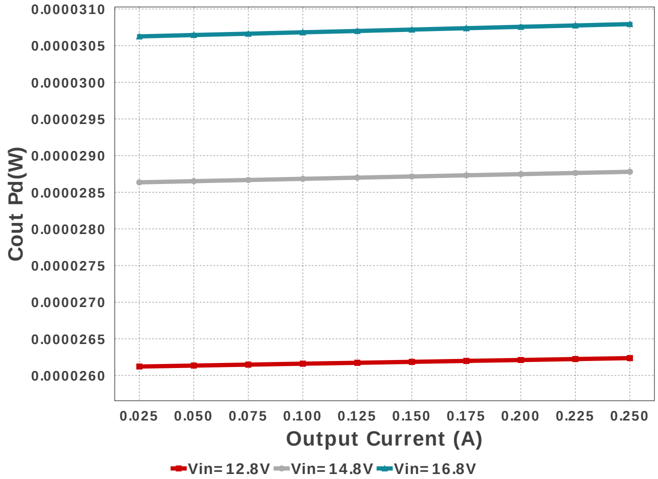
IC Ipk

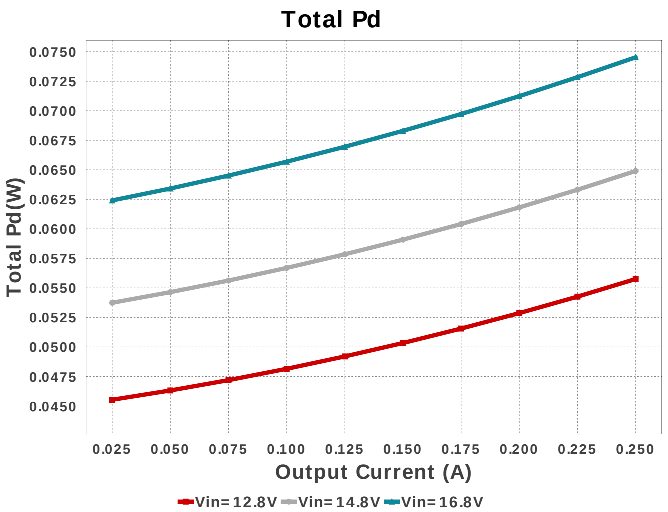


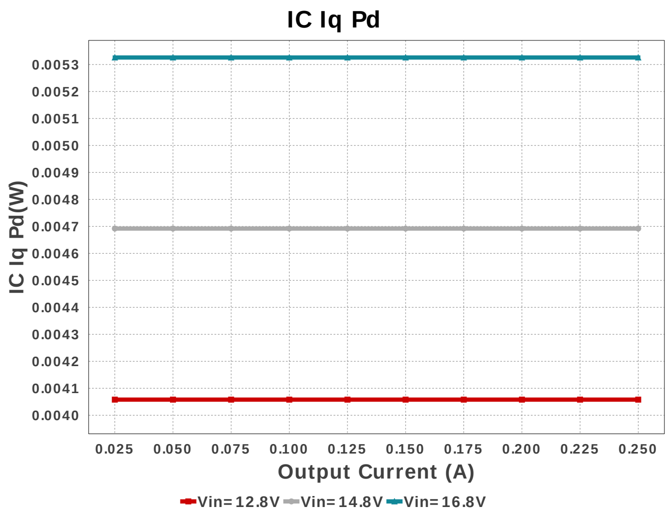
Cout IRMS

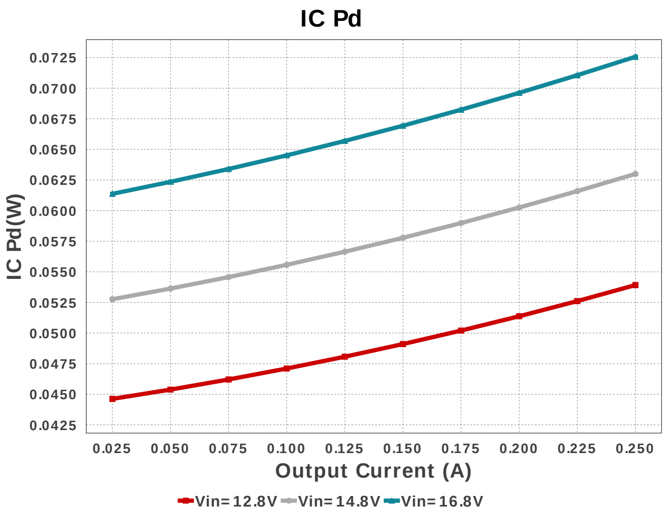


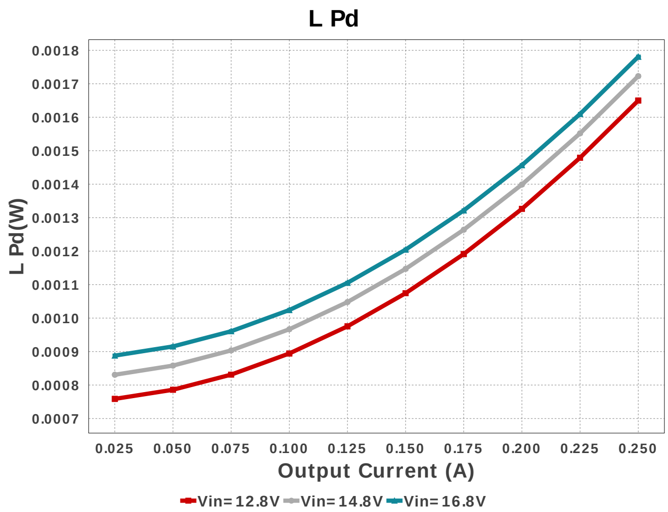
Cout Pd











Operating Values

#	Name	Value	Category	Description
1.	Cin IRMS	148.53 mA	Capacitor	Input capacitor RMS ripple current
2.	Cin Pd	55.153 µW	Capacitor	Input capacitor power dissipation
3.	Cout IRMS	248.169 mA	Capacitor	Output capacitor RMS ripple current
4.	Cout Pd	30.794 µW	Capacitor	Output capacitor power dissipation
5.	IC Ipk	679.842 mA	IC	Peak switch current in IC
6.	IC Iq Pd	5.326 mW	IC	IC Iq Pd
7.	IC Pd	72.565 mW	IC	IC power dissipation
8.	IC Tj	34.354 degC	IC	IC junction temperature
9.	ICThetaJA Effective	60.0 degC/W	IC	Effective IC Junction-to-Ambient Thermal Resistance
10.	Iin Avg	53.543 mA	IC	Average input current
11.	L Ipp	859.68 mA	Inductor	Peak-to-peak inductor ripple current
12.	L Pd	1.781 mW	Inductor	Inductor power dissipation
13.	Cin Pd	55.153 µW	Power	Input capacitor power dissipation
14.	Cout Pd	30.794 µW	Power	Output capacitor power dissipation
15.	IC Pd	72.565 mW	Power	IC power dissipation
16.	L Pd	1.781 mW	Power	Inductor power dissipation
17.	Total Pd	74.525 mW	Power	Total Power Dissipation
18.	BOM Count	9	System Information	Total Design BOM count
19.	Duty Cycle	19.742 %	System Information	Duty cycle
20.	Efficiency	91.715 %	System Information	Steady state efficiency
21.	FootPrint	233.0 mm^2	System Information	Total Foot Print Area of BOM components
22.	Frequency	340.0 kHz	System Information	Switching frequency
23.	Iout	250.0 mA	System Information	Iout operating point
24.	Mode	FCCM	System Information	PWM/PFM Mode

#	Name	Value	Category	Description
25.	Pout	825.0 mW	System Information	Total output power
26.	Total BOM	$3.76	System Information	Total BOM Cost
27.	Vin	16.8 V	System Information	Vin operating point
28.	Vout Actual	3.305 V	System Information	Vout Actual calculated based on selected voltage divider resistors
29.	Vout Tolerance	1.656 %	System Information	Vout Tolerance based on IC Tolerance (no load) and voltage divider resistors if applicable
30.	Vout p-p	7.439 mV	System Information	Peak-to-peak output ripple voltage

Design Inputs

Name	Value	Description
Iout	250.0 m	Maximum Output Current
VinMax	16.8	Maximum input voltage
VinMin	12.8	Minimum input voltage
Vout	3.3	Output Voltage
base_pn	TPS54308	Base Product Number
source	DC	Input Source Type
Ta	30.0	Ambient temperature

WEBENCH® Assembly

Component Testing

Some published data on components in datasheets such as Capacitor ESR and Inductor DC resistance is based on conservative values that will guarantee that the components always exceed the specification. For design purposes it is usually better to work with typical values. Since this data is not always available it is a good practice to measure the Capacitance and ESR values of Cin and Cout, and the inductance and DC resistance of L1 before assembly of the board. Any large discrepancies in values should be electrically simulated in WEBENCH to check for instabilities and thermally simulated in WebTHERM to make sure critical temperatures are not exceeded.

Soldering Component to Board

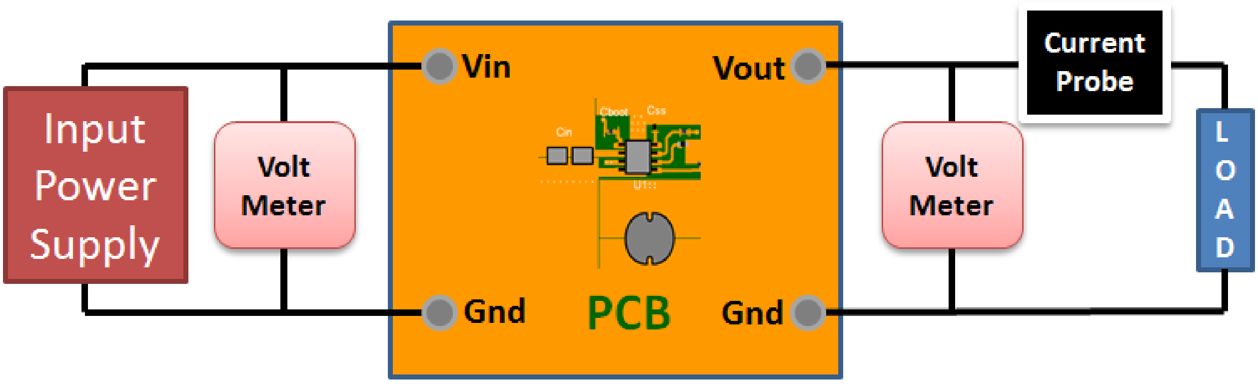
If board assembly is done in house it is best to tack down one terminal of a component on the board then solder the other terminal. For surface mount parts with large tabs, such as the DPAK, the tab on the back of the package should be pre-tinned with solder, then tacked into place by one of the pins. To solder the tab town to the board place the iron down on the board while resting against the tab, heating both surfaces simultaneously. Apply light pressure to the top of the plastic case until the solder flows around the part and the part is flush with the PCB. If the solder is not flowing around the board you may need a higher wattage iron (generally 25W to 30W is enough).

Initial Startup of Circuit

It is best to initially power up the board by setting the input supply voltage to the lowest operating input voltage 12.8V and set the input supply's current limit to zero. With the input supply off connect up the input supply to Vin and GND. Connect a digital volt meter and a load if needed to set the minimum Iout of the design from Vout and GND. Turn on the input supply and slowly turn up the current limit on the input supply. If the voltage starts to rise on the input supply continue increasing the input supply current limit while watching the output voltage. If the current increases on the input supply, but the voltage remains near zero, then there may be a short or a component misplaced on the board. Power down the board and visually inspect for solder bridges and recheck the diode and capacitor polarities. Once the power supply circuit is operational then more extensive testing may include full load testing, transient load and line tests to compare with simulation results.

Load Testing

The setup is the same as the initial startup, except that an additional digital voltmeter is connected between Vin and GND, a load is connected between Vout and GND and a current meter is connected in series between Vout and the load. The load must be able to handle at least rated output power + 50% (7.5 watts for this design). Ideally the load is supplied in the form of a variable load test unit. It can also be done in the form of suitably large power resistors. When using an oscilloscope to measure waveforms on the prototype board, the ground leads of the oscilloscope probes should be as short as possible and the area of the loop formed by the ground lead should be kept to a minimum. This will help reduce ground lead inductance and eliminate EMI noise that is not actually present in the circuit.



Design Assistance

1. Master key : E86007F5CFD5661C[v1]

2. **TPS54308** Product Folder : http://www.ti.com/product/TPS54308 : contains the data sheet and other resources.

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